ON Semiconductor®

Final Product/Process Change Notification

Document #: FPCN22948X
Issue Date: 17 Jun 2020

Title of Change:	Assembly and Test Transfer of NB3U23CMNTAG from SPEL to SBN with mold compound change.
Proposed First Ship date:	24 Sep 2020 or earlier if approved by customer
Contact Information:	Contact your local ON Semiconductor Sales Office or Eric.Rupnow@onsemi.com
PCN Samples Contact:	Contact your local ON Semiconductor Sales Office or <PCN.samples@onsemi.com>. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or Joe.Chapple@onsemi.com
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com
Marking of Parts/ Traceability of Change:	Affected products will be identified with date code code from new plant.
Change Category:	Assembly Change, Test Change
Change Sub-Category(s):	Manufacturing Site Change

Sites Affected:

ON Semiconductor Sites	**External Foundry/Subcon Sites**
ON Semiconductor Seremban, Malaysia	SPEL Semiconductor Limited

Description and Purpose:

This Final notification announces the transfer of assembly and test of NB3U23CMNTAG from SPEL Semiconductor Limited (SPEL) to

ON Semiconductor Seremban, Malaysia (SBN) which includes the change in lead frame design and mold material.

UDFN-6

	Before Change Description	**After Change Description**
Lead Frame	LF PPF Frame (COL design)	LF PPF Frame (COL design)
Die Attach	8006NS	8006NS
Mold Compound	CEL9220ZHF10L	G760
Assembly Site	SPEL Semiconductor Limited (SPEL)	ON Semiconductor Seremban, Malaysia (SBN)
Test Site	SPEL Semiconductor Limited (SPEL)	ON Semiconductor Seremban, Malaysia (SBN)

No package dimension change and no product performance change.

Reliability Data Summary:

QV DEVICE NAME: NB3U23CMNTAG
RMS : S59248
PACKAGE : UDFN-6

Test	Specification	Condition	Interval	Results
HTOL	JESD22-A108	Ta= 125°C, 120% nominal Vcc	504 hrs	0/240
TC	JESD22-A104	Ta= -65°C to + 150°C	500 cyc	0/240
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0/240
UHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/240
PC	J-STD-020 JESD-A113	MSL 1 @ 260°C		0/240
RSH	JESD22-B106	Ta = 265C, 10 sec		0/90
SD	JSTD002B	Ta = 245C, 10 sec		0/45

Electrical Characteristics Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: *Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the* ***PCN Customized Portal.***

Part Number	Qualification Vehicle
NB3U23CMNTAG	NB3U23CMNTAG